

August 2015

# MOC3031M, MOC3032M, MOC3033M, MOC3041M, MOC3042M, MOC3043M 6-Pin DIP Zero-Cross Triac Driver Output Optocoupler (250/400 Volt Peak)

## **Features**

- Simplifies Logic Control of 115 VAC Power
- · Zero Voltage Crossing
- dv/dt of 2000 V/µs Typical, 1000 V/µs Guaranteed
- · Peak Blocking Voltage
  - 250 V, MOC303XM
  - 400 V, MOC304XM
- · Safety and Regulatory Approvals
  - UL1577, 4,170 VAC<sub>RMS</sub> for 1 Minute
  - DIN EN/IEC60747-5-5

# **Applications**

- · Solenoid/Valve Controls
- · Lighting Controls
- · Static Power Switches
- · AC Motor Drives
- · Temperature Controls
- · E.M. Contactors
- AC Motor Starters
- Solid State Relays

# Description

The MOC303XM and MOC304XM devices consist of a GaAs infrared emitting diode optically coupled to a monolithic silicon detector performing the function of a zero voltage crossing bilateral triac driver.

They are designed for use with a triac in the interface of logic systems to equipment powered from 115 VAC lines, such as teletypewriters, CRTs, solid-state relays, industrial controls, printers, motors, solenoids and consumer appliances, etc.

#### **Schematic**

# ANODE 1 CATHODE 2 N/C 3 \*DO NOT CONNECT (TRIAC SUBSTRATE)

Figure 1. Schematic

# Package Outlines

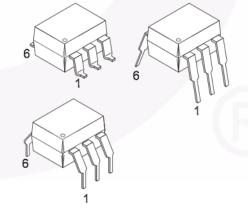


Figure 2. Package Outlines

# Safety and Insulation Ratings

As per DIN EN/IEC 60747-5-5, this optocoupler is suitable for "safe electrical insulation" only within the safety limit data. Compliance with the safety ratings shall be ensured by means of protective circuits.

Parameter	Characteristics	
Installation Classifications per DIN VDE	< 150 V <sub>RMS</sub>	I–IV
0110/1.89 Table 1, For Rated Mains Voltage	< 300 V <sub>RMS</sub>	I–IV
Climatic Classification		40/85/21
Pollution Degree (DIN VDE 0110/1.89)		2
Comparative Tracking Index		175

Parameter	Value	Unit
Input-to-Output Test Voltage, Method A, $V_{IORM} \times 1.6 = V_{PR}$ , Type and Sample Test with $t_m = 10$ s, Partial Discharge < 5 pC	1275	V <sub>peak</sub>
Input-to-Output Test Voltage, Method B, $V_{IORM}$ x 1.875 = $V_{PR}$ , 100% Production Test with $t_m$ = 1 s, Partial Discharge < 5 pC	1594	V <sub>peak</sub>
Maximum Working Insulation Voltage	850	$V_{peak}$
Highest Allowable Over-Voltage	6000	V <sub>peak</sub>
External Creepage	≥ 7	mm
External Clearance	≥ 7	mm
External Clearance (for Option TV, 0.4" Lead Spacing)	≥ 10	mm
Distance Through Insulation (Insulation Thickness)	≥ 0.5	mm
Insulation Resistance at T <sub>S</sub> , V <sub>IO</sub> = 500 V	> 10 <sup>9</sup>	Ω
	Input-to-Output Test Voltage, Method A, V <sub>IORM</sub> x 1.6 = V <sub>PR</sub> , Type and Sample Test with t <sub>m</sub> = 10 s, Partial Discharge < 5 pC  Input-to-Output Test Voltage, Method B, V <sub>IORM</sub> x 1.875 = V <sub>PR</sub> , 100% Production Test with t <sub>m</sub> = 1 s, Partial Discharge < 5 pC  Maximum Working Insulation Voltage  Highest Allowable Over-Voltage  External Creepage  External Clearance  External Clearance (for Option TV, 0.4" Lead Spacing)  Distance Through Insulation (Insulation Thickness)	$\begin{array}{ll} \mbox{Input-to-Output Test Voltage, Method A, $V_{IORM}$ x 1.6 = $V_{PR}$,} \\ \mbox{Type and Sample Test with $t_m$ = 10 s, Partial Discharge < 5 pC} \\ \mbox{Input-to-Output Test Voltage, Method B, $V_{IORM}$ x 1.875 = $V_{PR}$,} \\ \mbox{100% Production Test with $t_m$ = 1 s, Partial Discharge < 5 pC} \\ \mbox{Maximum Working Insulation Voltage} \\ \mbox{Highest Allowable Over-Voltage} \\ \mbox{External Creepage} \\ \mbox{External Clearance} \\ \mbox{External Clearance (for Option TV, 0.4" Lead Spacing)} \\ \mbox{Distance Through Insulation (Insulation Thickness)} \\ \mbox{$\geq 0.5$} \\  \end{array}$

# **Absolute Maximum Ratings**

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.  $T_A = 25^{\circ}C$  unless otherwise specified.

Symbol	Parameters	Device	Value	Unit
TOTAL DE	VICE			
T <sub>STG</sub>	Storage Temperature	All	-40 to +150	°C
T <sub>OPR</sub>	Operating Temperature	All	-40 to +85	°C
TJ	Junction Temperature Range	All	-40 to +100	°C
T <sub>SOL</sub>	Lead Solder Temperature	All	260 for 10 seconds	°C
	Total Device Power Dissipation at 25°C Ambient	All	250	mW
$P_{D}$	Derate Above 25°C	All	2.94	mW/°C
EMITTER				•
I <sub>F</sub>	Continuous Forward Current	All	60	mA
V <sub>R</sub>	Reverse Voltage	All	6	V
D	Total Power Dissipation at 25°C Ambient	All	120	mW
$P_D$	Derate Above 25°C	All	1.41	mW/°C
DETECTOR	2			
W	Off State Output Tampinal Valtage	MOC3031M MOC3032M MOC3033M	250	V
$V_{DRM}$	Off-State Output Terminal Voltage	MOC3041M MOC3042M MOC3043M	400	V
I <sub>TSM</sub>	Peak Repetitive Surge Current (PW = 100 μs, 120 pps)	All	1	А
В	Total Power Dissipation at 25°C Ambient	All	150	mW
$P_{D}$	Derate Above 25°C	All	1.76	mW/°C

# **Electrical Characteristics**

T<sub>A</sub> = 25°C unless otherwise specified.

# **Individual Component Characteristics**

Symbol	Parameters	Test Conditions	Device	Min.	Тур.	Max.	Unit
EMITTER	EMITTER						
V <sub>F</sub>	Input Forward Voltage	I <sub>F</sub> = 30 mA	All		1.25	1.50	V
I <sub>R</sub>	Reverse Leakage Current	V <sub>R</sub> = 6 V	All		0.01	100	μΑ
DETECTO	DETECTOR						
I <sub>DRM1</sub>	Peak Blocking Current, Either Direction	Rated V <sub>DRM</sub> , I <sub>F</sub> = 0 <sup>(1)</sup>	All			100	nA
V <sub>TM</sub>	Peak On-State Voltage, Either Direction	I <sub>TM</sub> = 100 mA peak, I <sub>F</sub> = 0	All		1.8	3.0	V
dv/dt	Critical Rate of Rise of Off-State Voltage	I <sub>F</sub> = 0 (Figure 11) <sup>(2)</sup>	All	1000	2000		V/µs

#### **Transfer Characteristics**

Symbol	DC Characteristics	Test Conditions	Device	Min.	Тур.	Max.	Unit
			MOC3031M MOC3041M			15	
I <sub>FT</sub>	LED Trigger Current	Main Terminal Voltage = 3 V <sup>(3)</sup>	MOC3032M MOC3042M			10	mA
			MOC3033M MOC3043M			5	
I <sub>H</sub>	Holding Current, Either Direction		All		400		μА

## Zero Crossing Characteristics

Symbol	Characteristics	Test Conditions	Device	Min.	Тур.	Max.	Unit
V <sub>IH</sub>	Inhibit Voltage	I <sub>F</sub> = rated I <sub>FT</sub> , MT1-MT2 voltage above which device will not trigger off-state	All			20	V
I <sub>DRM2</sub>	Leakage in Inhibited State	I <sub>F</sub> = rated I <sub>FT</sub> , rated V <sub>DRM</sub> off-state	All			2	mA

#### **Isolation Characteristics**

Symbol	Parameter	Test Conditions	Device	Min.	Тур.	Max.	Unit
$V_{ISO}$	Isolation Voltage <sup>(4)</sup>	t = 1 Minute	All	4170			VAC <sub>RMS</sub>

### Notes:

- 1. Test voltage must be applied within dv/dt rating.
- 2. This is static dv/dt. See Figure 11 for test circuit. Commutating dv/dt is a function of the load-driving thyristor(s) only.
- 3. All devices are guaranteed to trigger at an I<sub>F</sub> value less than or equal to max I<sub>FT</sub>. Therefore, recommended operating I<sub>F</sub> lies between max I<sub>FT</sub> (15 mA for MOC3031M and MOC3041M, 10 mA for MOC3032M and MOC3042M, 5 mA for MOC3033M and MOC3043M) and absolute maximum I<sub>F</sub> (60 mA).
- 4. Isolation voltage, V<sub>ISO</sub>, is an internal device dielectric breakdown rating. For this test, pins 1 and 2 are common, and pins 4, 5 and 6 are common.

# **Typical Performance Curves**

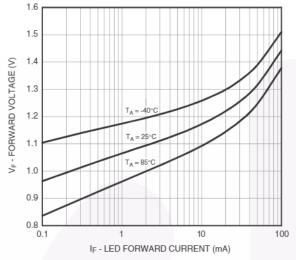


Figure 3. LED Forward Voltage vs. Forward Current

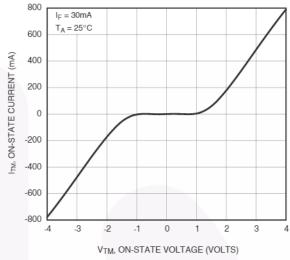


Figure 4. On-State Characteristics

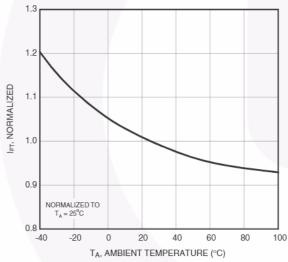


Figure 5. Trigger Current vs. Temperature

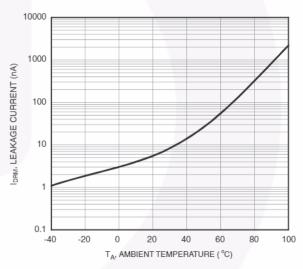


Figure 6. Leakage Current, I<sub>DRM</sub> vs. Temperature

# Typical Performance Curves (Continued)

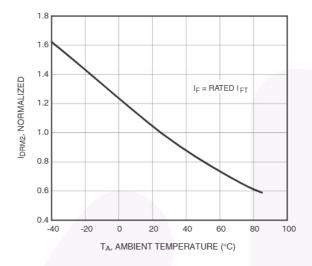


Figure 7.  $I_{DRM2}$  - Leakage in Inhibit State vs. Temperature

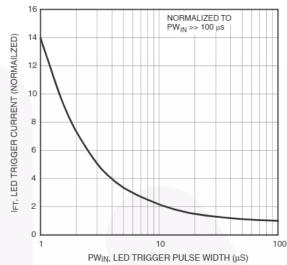


Figure 8. LED Current Required to Trigger vs. LED Pulse Width

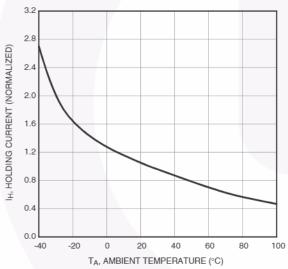


Figure 9. Holding Current, I<sub>H</sub> vs. Temperature

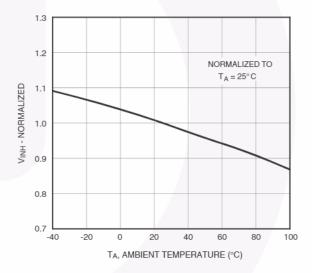


Figure 10. Inhibit Voltage vs. Temperature

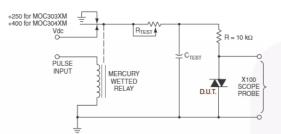


Figure 11. Static dv/dt Test Circuit

- The mercury wetted relay provides a high speed repeated pulse to the D.U.T.
- 100x scope probes are used, to allow high speeds and voltages.
- 3. The worst-case condition for static dv/dt is established by triggering the D.U.T. with a normal LED input current, then removing the current. The variable R<sub>TEST</sub> allows the dv/dt to be gradually increased until the D.U.T. continues to trigger in response to the applied voltage pulse, even after the LED current has been removed. The dv/dt is then decreased until the D.U.T stops triggering. τ<sub>RC</sub> is measured at this point and recorded.

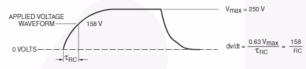


Figure 12. Static dv/dt Test Waveform (MOC3031M, MOC3032M, MOC3033M)

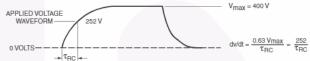


Figure 13. Static dv/dt Test Waveform (MOC3041M, MOC3042M, MOC3043M)

Typical circuit (Fig 14, 15) for use when hot line switching is required. In this circuit the "hot" side of the line is switched and the load connected to the cold or neutral side. The load may be connected to either the neutral or hot line.

 $R_{in}$  is calculated so that  $I_F$  is equal to the rated  $I_{FT}$  of the part, 5mA for the MOC3033M and MOC3043M, 10mA for the MOC3032M and MOC3042M, or 15mA for the MOC3031M and MOC3041M. The 39 ohm resistor and 0.01 $\mu$ F capacitor are for snubbing of the triac and may or may not be necessary depending upon the particular triac and load used.

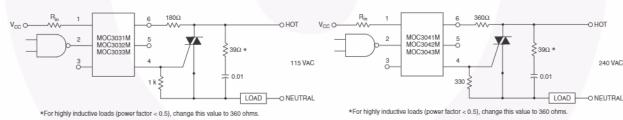


Figure 14. Hot-Line Switching Application Circuit (MOC3031M, MOC3032M, MOC3033M)

Figure 15. Hot-Line Switching Application Circuit (MOC3041M, MOC3042M, MOC3043M)

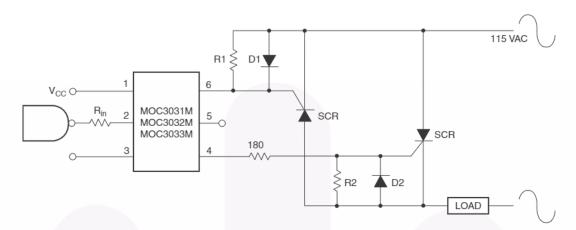


Figure 16. Inverse-Parallel SCR Driver Circuit (MOC3031M, MOC3032M, MOC3033M)

Suggested method of firing two, back-to-back SCR's with a Fairchild triac driver. Diodes can be 1N4001; resistors, R1 and R2, are optional  $1k\Omega$ .

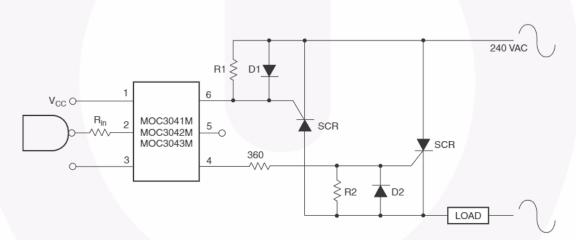


Figure 17. Inverse-Parallel SCR Driver Circuit (MOC3041M, MOC3042M, MOC3043M)

Suggested method of firing two, back-to-back SCR's with a Fairchild triac driver. Diodes can be 1N4001; resistors, R1 and R2, are optional  $330\Omega$ .

#### Note:

This optoisolator should not be used to drive a load directly. It is intended to be a trigger device only.

# **Reflow Profile**

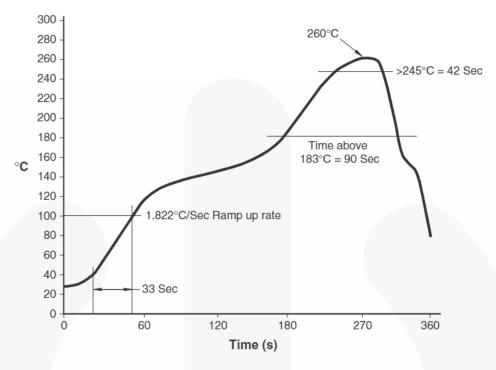


Figure 18. Reflow Profile

# Ordering Information(5)

Part Number	Package	Packing Method
MOC3031M	DIP 6-Pin	Tube (50 Units)
MOC3031SM	SMT 6-Pin (Lead Bend)	Tube (50 Units)
MOC3031SR2M	SMT 6-Pin (Lead Bend)	Tape and Reel (1000 Units)
MOC3031VM	DIP 6-Pin, DIN EN/IEC60747-5-5 Option	Tube (50 Units)
MOC3031SVM	SMT 6-Pin (Lead Bend), DIN EN/IEC60747-5-5 Option	Tube (50 Units)
MOC3031SR2VM	SMT 6-Pin (Lead Bend), DIN EN/IEC60747-5-5 Option	Tape and Reel (1000 Units)
MOC3031TVM	DIP 6-Pin, 0.4" Lead Spacing, DIN EN/IEC60747-5-5 Option	Tube (50 Units)

#### Note:

The product orderable part number system listed in this table also applies to the MOC3032M, MOC3033M, MOC3041M, MOC3042M, and MOC3043M product families.

# **Marking Information**

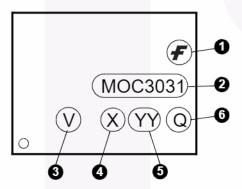
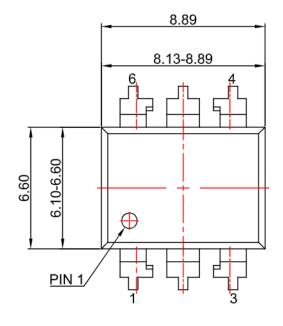
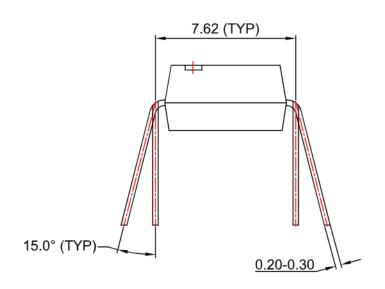
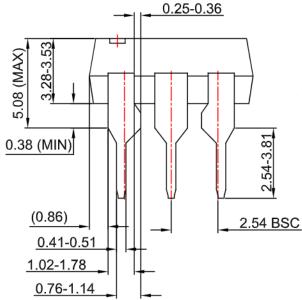


Figure 19. Top Mark

Тор Ма	Top Mark Definitions						
1	Fairchild Logo						
2	Device Number						
3	DIN EN/IEC60747-5-5 Option (only appears on component ordered with this option)						
4	One-Digit Year Code, e.g., '5'						
5	Two-Digit Work Week, Ranging from '01' to '53'						
6	Assembly Package Code						



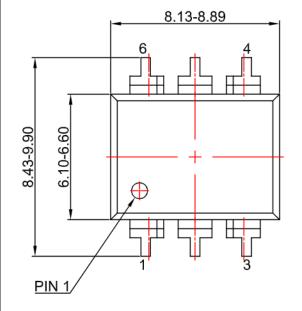


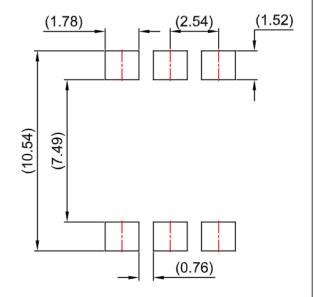


# NOTES:

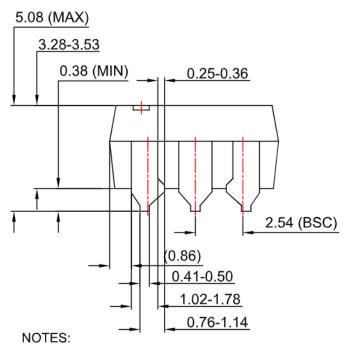
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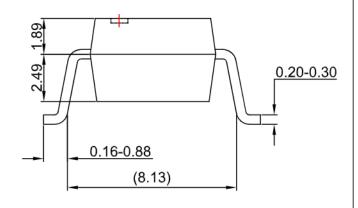






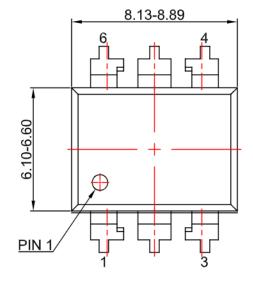
LAND PATTERN RECOMMENDATION

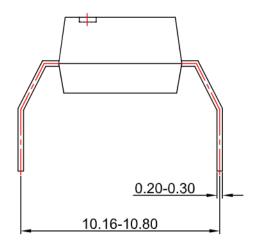


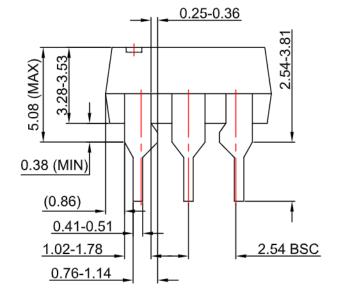


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#### PRODUCT STATUS DEFINITIONS

#### Definition of Terms

Definition of Terms					
Datasheet Identification	Product Status	Definition			
Advance Information	Formative / In Design	Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.			
Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.			
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.			
Obsolete	Not In Production	Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.			

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